

# FOD2711A

## Optically Isolated Error Amplifier

### Features

- Optocoupler, precision reference and error amplifier in single package
- 1.240V  $\pm$  1% reference
- CTR 100% to 200%
- 5,000V RMS isolation
- UL approval E90700, Volume 2

### Applications

- Power supplies regulation
- DC to DC converters

### Description

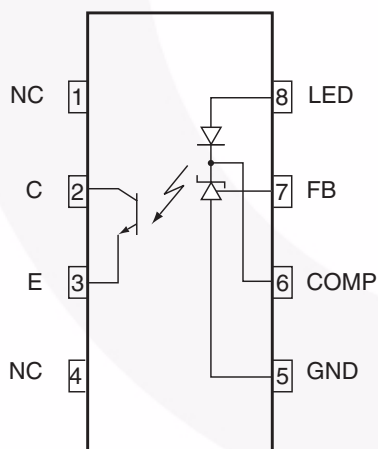
The FOD2711A Optically Isolated Amplifier consists of the popular AZ431L precision programmable shunt reference and an optocoupler. The optocoupler is a gallium arsenide (GaAs) light emitting diode optically coupled to a silicon phototransistor. The reference voltage tolerance is 1%. The current transfer ratio (CTR) ranges from 100% to 200%.

It is primarily intended for use as the error amplifier/reference voltage/optocoupler function in isolated AC to DC power supplies and dc/dc converters.

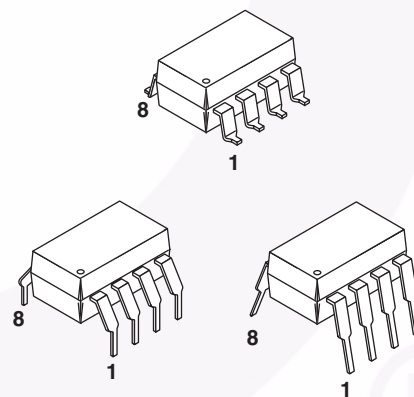
When using the FOD2711A, power supply designers can reduce the component count and save space in tightly packaged designs. The tight tolerance reference eliminates the need for adjustments in many applications.

The device comes in a 8-pin dip white package.

### Functional Block Diagram



### Package Outlines

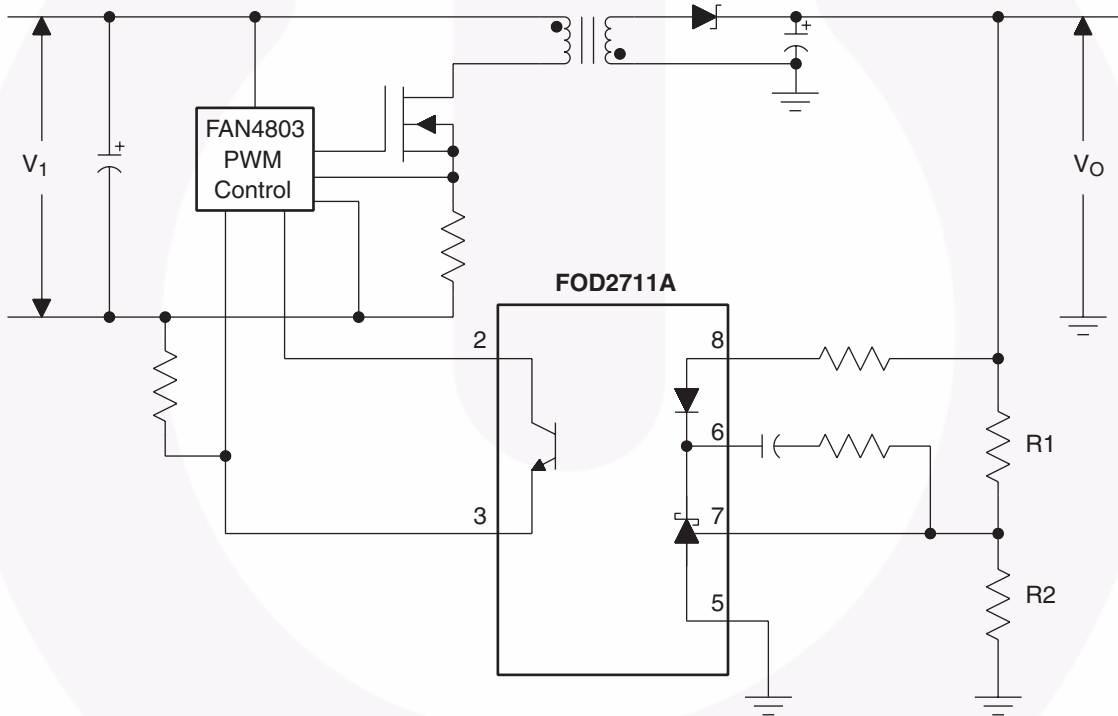


### Pin Definitions

| Pin Number | Pin Name | Pin Description   |
|------------|----------|---|
| 1          | NC       | Not connected   |
| 2          | C        | Phototransistor Collector   |
| 3          | E        | Phototransistor Emitter   |
| 4          | NC       | Not connected   |
| 5          | GND      | Ground  |
| 6          | COMP     | Error Amplifier Compensation. This pin is the output of the error amplifier.* |
| 7          | FB       | Voltage Feedback. This pin is the inverting input to the error amplifier      |
| 8          | LED      | Anode LED. This pin is the input to the light emitting diode.                 |

\*The compensation network must be attached between pins 6 and 7.

### Typical Application



**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol           | Parameter                                   | Value           | Units            |
|------------------|---|-----------------|------------------|
| $T_{\text{STG}}$ | Storage Temperature                         | -40 to +125     | $^\circ\text{C}$ |
| $T_{\text{OPR}}$ | Operating Temperature                       | -40 to +85      | $^\circ\text{C}$ |
| $T_{\text{SOL}}$ | Lead Solder Temperature                     | 260 for 10 sec. | $^\circ\text{C}$ |
| $V_{\text{LED}}$ | Input Voltage                               | 13.2            | V                |
| $I_{\text{LED}}$ | Input DC Current                            | 20              | mA               |
| $V_{\text{CEO}}$ | Collector-Emitter Voltage                   | 30              | V                |
| $V_{\text{ECO}}$ | Emitter-Collector Voltage                   | 7               | V                |
| $I_{\text{C}}$   | Collector Current                           | 50              | mA               |
| PD1              | Input Power Dissipation <sup>(1)</sup>      | 145             | mW               |
| PD2              | Transistor Power Dissipation <sup>(2)</sup> | 85              | mW               |
| PD3              | Total Power Dissipation <sup>(3)</sup>      | 145             | mW               |

**Notes:**

1. Derate linearly from  $25^\circ\text{C}$  at a rate of  $2.42\text{mW}/^\circ\text{C}$
2. Derate linearly from  $25^\circ\text{C}$  at a rate of  $1.42\text{mW}/^\circ\text{C}$ .
3. Derate linearly from  $25^\circ\text{C}$  at a rate of  $2.42\text{mW}/^\circ\text{C}$ .

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)**Input Characteristics**

| Symbol                                   | Parameter  | Test Conditions   | Min.  | Typ.* | Max.  | Unit          |
|--|--|---|-------|-------|-------|---------------|
| $V_F$                                    | LED Forward Voltage  | $I_{LED} = 10\text{mA}$ , $V_{COMP} = V_{FB}$ (Fig. 1)                              |       |       | 1.5   | V             |
| $V_{REF}$                                | Reference Voltage<br>-40°C to +85°C<br>25°C                  | $V_{COMP} = V_{FB}$ , $I_{LED} = 10\text{mA}$ (Fig.1)                               | 1.221 |       | 1.259 | V             |
|  |  |   | 1.228 | 1.240 | 1.252 |               |
| $V_{REF(DEV)}$                           | Deviation of $V_{REF}$ Over Temperature <sup>(4)</sup>       | $T_A = -40$ to $+85^\circ\text{C}$  |       | 4     | 12    | mV            |
| $\frac{\Delta V_{REF}}{\Delta V_{COMP}}$ | Ratio of Vref Variation to the Output of the Error Amplifier | $I_{LED} = 10\text{mA}$ , $V_{COMP} = V_{REF}$ to 12V (Fig. 2)                      |       | -1.5  | -2.7  | mV/V          |
| $I_{REF}$                                | Feedback Input Current                                       | $I_{LED} = 10\text{mA}$ , $R1 = 10\text{k}\Omega$ (Fig. 3)                          |       | 0.15  | 0.5   | $\mu\text{A}$ |
| $I_{REF(DEV)}$                           | Deviation of $I_{REF}$ Over Temperature <sup>(4)</sup>       | $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$                                    |       | 0.15  | 0.3   | $\mu\text{A}$ |
| $I_{LED(MIN)}$                           | Minimum Drive Current  | $V_{COMP} = V_{FB}$ (Fig. 1)  |       | 55    | 80    | $\mu\text{A}$ |
| $I_{(OFF)}$                              | Off-State Error Amplifier Current                            | $V_{LED} = 6\text{V}$ , $V_{FB} = 0$ (Fig. 4)                                       |       | 0.001 | 0.1   | $\mu\text{A}$ |
| $ Z_{OUT} $                              | Error Amplifier Output Impedance <sup>(5)</sup>              | $V_{COMP} = V_{FB}$ , $I_{LED} = 0.1\text{mA}$ to $15\text{mA}$ , $f < 1\text{KHZ}$ |       | 0.25  |       | $\Omega$      |

**Output Characteristics**

| Symbol     | Parameter                           | Test Conditions                | Min. | Typ. | Max. | Unit |
|------------|-------------------------------------|--------------------------------|------|------|------|------|
| $I_{CEO}$  | Collector Dark Current              | $V_{CE} = 10\text{V}$ (Fig. 5) |      |      | 50   | nA   |
| $BV_{ECO}$ | Emitter-Collector Voltage Breakdown | $I_E = 100\mu\text{A}$         | 7    |      |      | V    |
| $BV_{CEO}$ | Collector-Emitter Voltage Breakdown | $I_C = 1.0\text{mA}$           | 70   |      |      | V    |

**Transfer Characteristics**

| Symbol        | Parameter                            | Test Conditions   | Min. | Typ. | Max. | Unit |
|---------------|--------------------------------------|---|------|------|------|------|
| CTR           | Current Transfer Ratio               | $I_{LED} = 10\text{mA}$ , $V_{COMP} = V_{FB}$ , $V_{CE} = 5\text{V}$ (Fig. 6) | 100  |      | 200  | %    |
| $V_{CE(SAT)}$ | Collector-Emitter Saturation Voltage | $I_{LED} = 10\text{mA}$ , $V_{COMP} = V_{FB}$ , $I_C = 2.5\text{mA}$ (Fig. 6) |      |      | 0.4  | V    |

**Notes:**

4. The deviation parameters  $V_{REF(DEV)}$  and  $I_{REF(DEV)}$  are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage,  $\Delta V_{REF}$ , is defined as:

$$|\Delta V_{REF}|(\text{ppm}/^\circ\text{C}) = \frac{\{V_{REF(DEV)}/V_{REF}(T_A = 25^\circ\text{C})\} \times 10^6}{\Delta T_A}$$

where  $\Delta T_A$  is the rated operating free-air temperature range of the device.

5. The dynamic impedance is defined as  $|Z_{OUT}| = \Delta V_{COMP} / \Delta I_{LED}$ . When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by:

$$|Z_{OUT, TOT}| = \frac{\Delta V}{\Delta I} \approx |Z_{OUT}| \times \left[ 1 + \frac{R1}{R2} \right]$$

**Electrical Characteristics** (Continued) ( $T_A = 25^\circ\text{C}$  unless otherwise specified)**Isolation Characteristics**

| Symbol    | Parameter                               | Test Conditions   | Min. | Typ.      | Max. | Unit          |
|-----------|---|---|------|-----------|------|---------------|
| $I_{I-O}$ | Input-Output Insulation Leakage Current | RH = 45%, $T_A = 25^\circ\text{C}$ , $t = 5\text{s}$ ,<br>$V_{I-O} = 3000\text{ VDC}^{(6)}$ |      |           | 1.0  | $\mu\text{A}$ |
| $V_{ISO}$ | Withstand Insulation Voltage            | RH $\leq 50\%$ , $T_A = 25^\circ\text{C}$ , $t = 1\text{ min.}^{(6)}$                       | 5000 |           |      | Vrms          |
| $R_{I-O}$ | Resistance (Input to Output)            | $V_{I-O} = 500\text{ VDC}^{(6)}$  |      | $10^{12}$ |      | $\Omega$      |

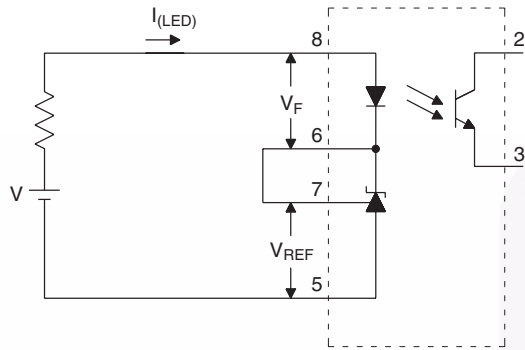
**Switching Characteristics**

| Symbol | Parameter                                     | Test Conditions  | Min. | Typ. | Max. | Unit                    |
|--------|---|--|------|------|------|-------------------------|
| BW     | Bandwidth                                     | (Fig. 7)   |      | 10   |      | kHZ                     |
| CMH    | Common Mode Transient Immunity at Output HIGH | $I_{LED} = 0\text{mA}$ , $ V_{cm}  = 10\text{ V}_{PP}$ ,<br>$R_L = 2.2\text{k}\Omega^{(7)}$ (Fig. 8) |      | 1.0  |      | $\text{kV}/\mu\text{s}$ |
| CML    | Common Mode Transient Immunity at Output LOW  | $I_{LED} = 1\text{mA}$ , $ V_{cm}  = 10\text{ V}_{PP}$ ,<br>$R_L = 2.2\text{k}\Omega^{(7)}$ (Fig. 8) |      | 1.0  |      | $\text{kV}/\mu\text{s}$ |

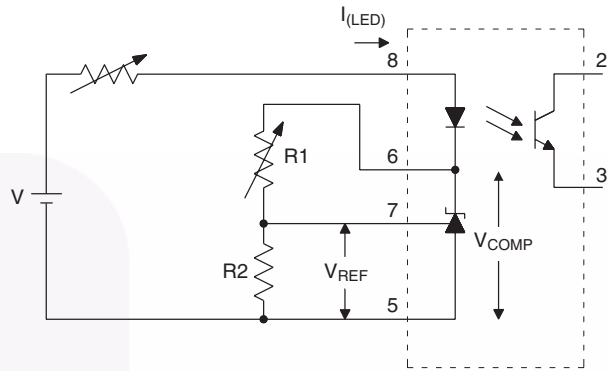
**Notes:**

- Device is considered as a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
- Common mode transient immunity at output high is the maximum tolerable (positive)  $dV_{cm}/dt$  on the leading edge of the common mode impulse signal,  $V_{cm}$ , to assure that the output will remain high. Common mode transient immunity at output low is the maximum tolerable (negative)  $dV_{cm}/dt$  on the trailing edge of the common pulse signal,  $V_{cm}$ , to assure that the output will remain low.

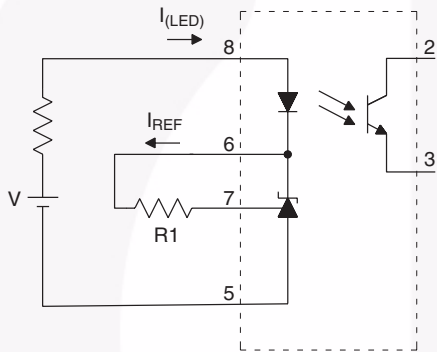
**Test Circuits**



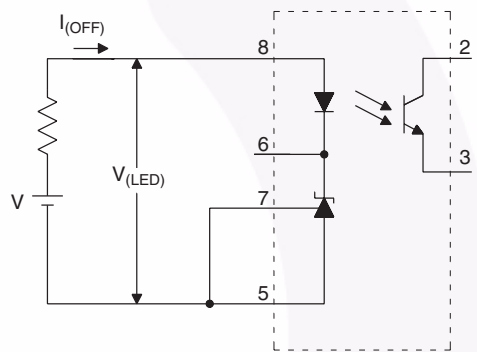
**Figure 1.  $V_{REF}$ ,  $V_F$ ,  $I_{LED}$  (min.) Test Circuit**



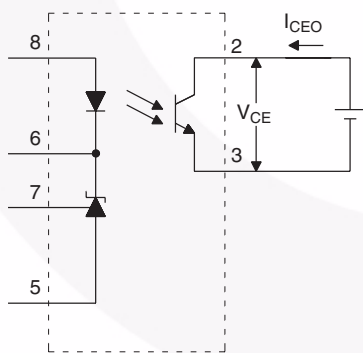
**Figure 2.  $\Delta V_{REF} / \Delta V_{COMP}$  Test Circuit**



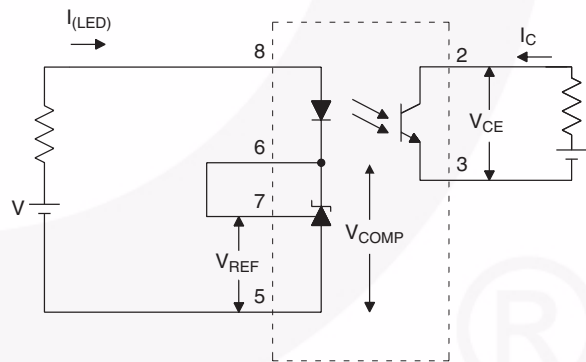
**Figure 3.  $I_{REF}$  Test Circuit**



**Figure 4.  $I_{(OFF)}$  Test Circuit**



**Figure 5.  $I_{CEO}$  Test Circuit**



**Figure 6.  $CTR$ ,  $V_{CE(sat)}$  Test Circuit**

Test Circuits (Continued)

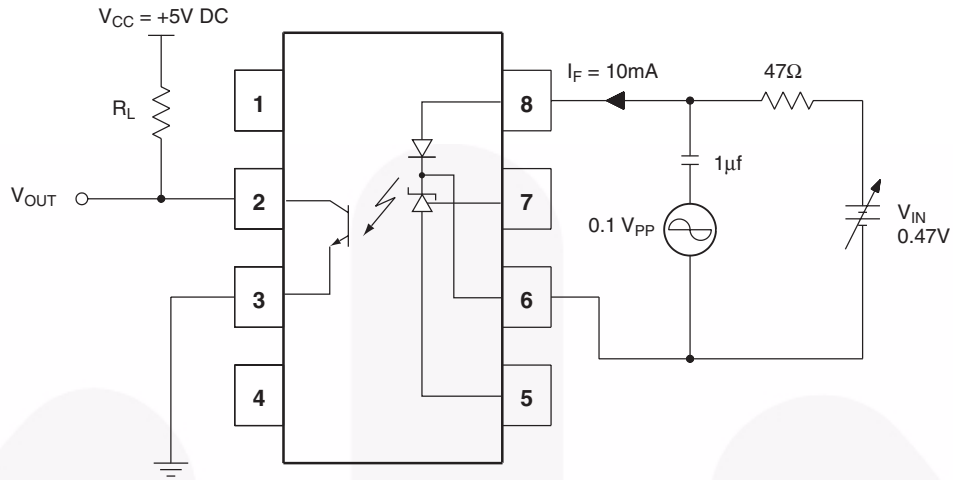


Figure 7. Frequency Response Test Circuit

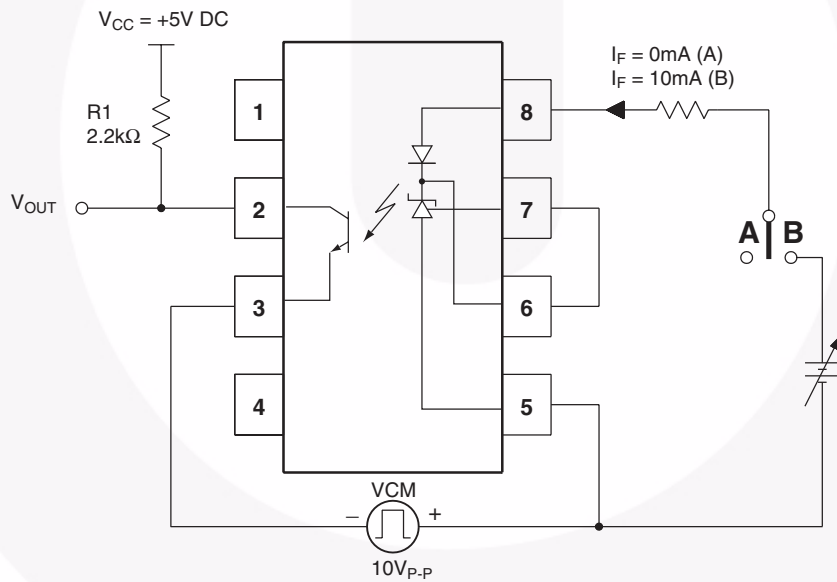
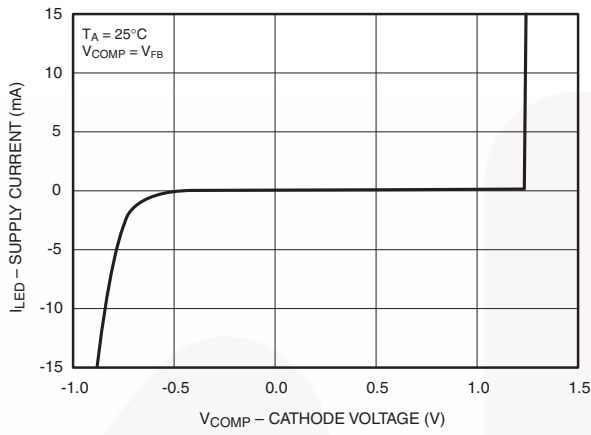


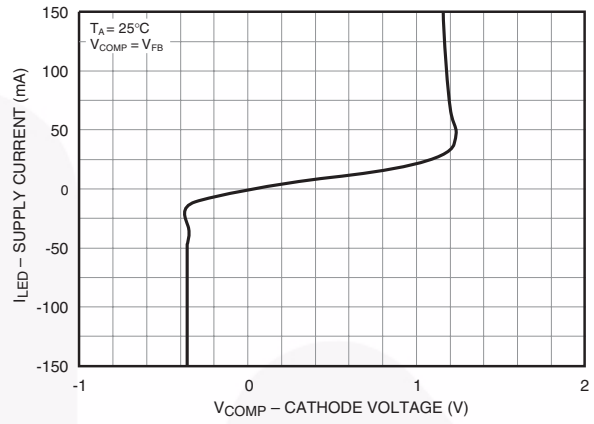
Figure 8. CMH and CML Test Circuit

## Typical Performance Curves

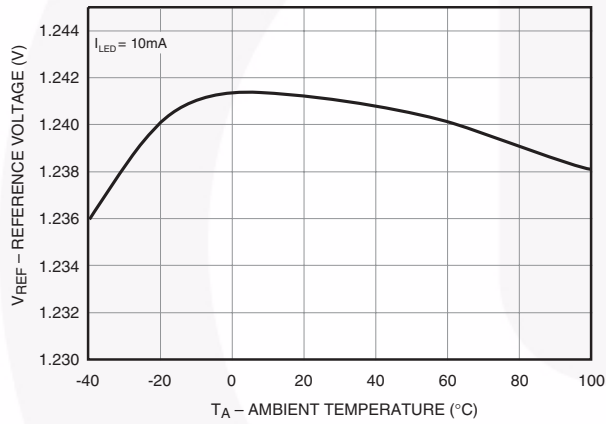
**Fig. 9a LED Current vs. Cathode Voltage**



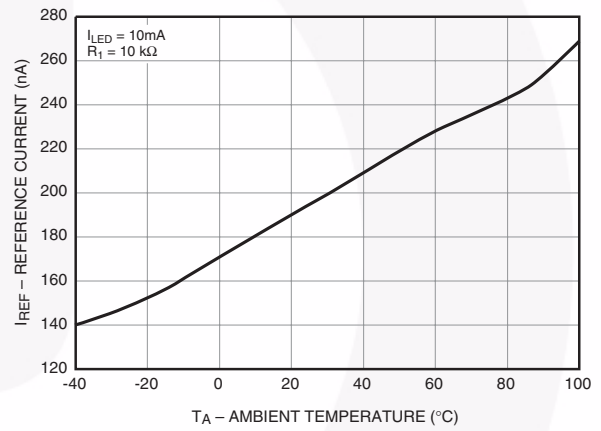
**Fig. 9b LED Current vs. Cathode Voltage**



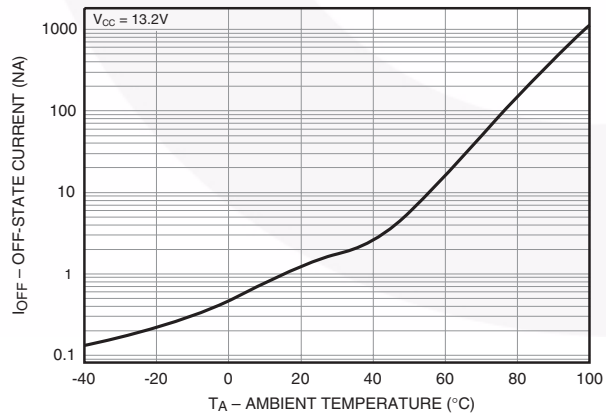
**Fig. 10 Reference Voltage vs. Ambient Temperature**



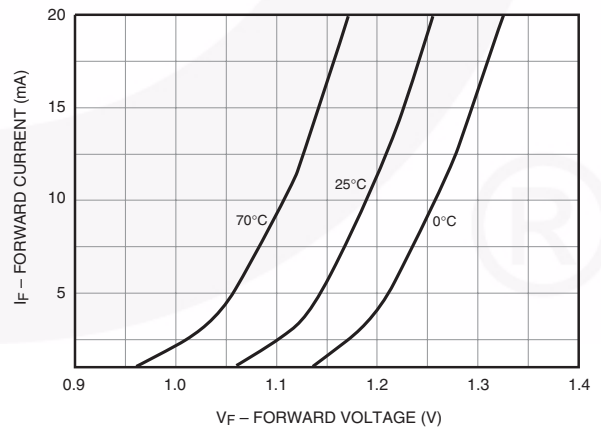
**Fig. 11 Reference Current vs. Ambient Temperature**



**Fig. 12 Off-State Current vs. Ambient Temperature**



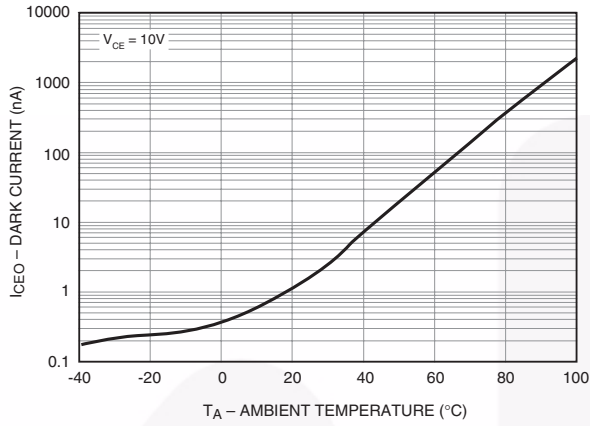
**Fig. 13 Forward Current vs. Forward Voltage**



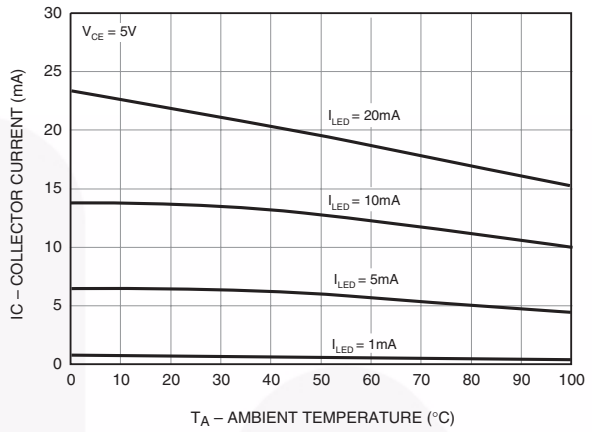


## Typical Performance Curves (Continued)

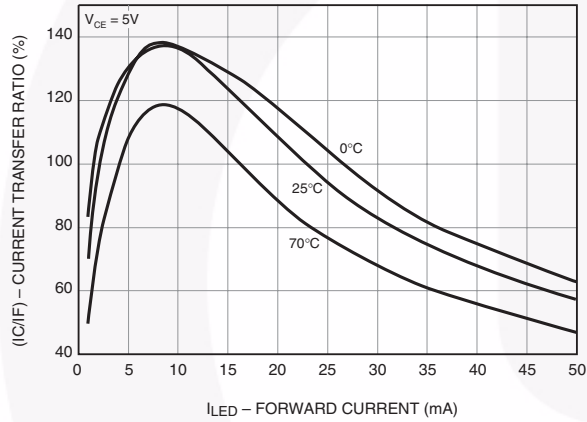
**Fig. 14 Dark Current vs. Ambient Temperature**



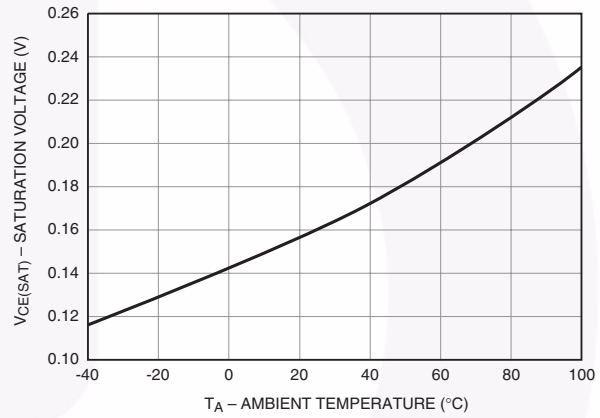
**Fig. 15 Collector Current vs. Ambient Temperature**



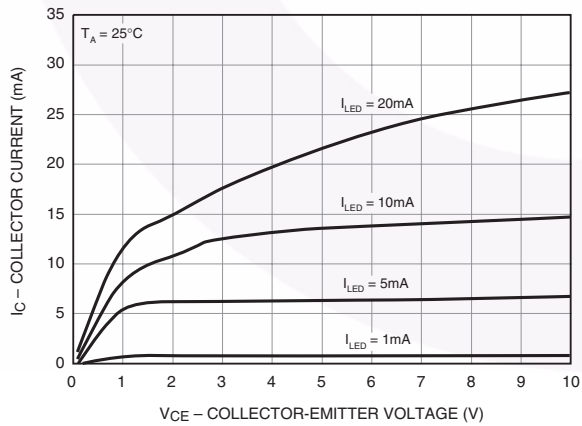
**Fig. 16 Current Transfer Ratio vs. LED Current**



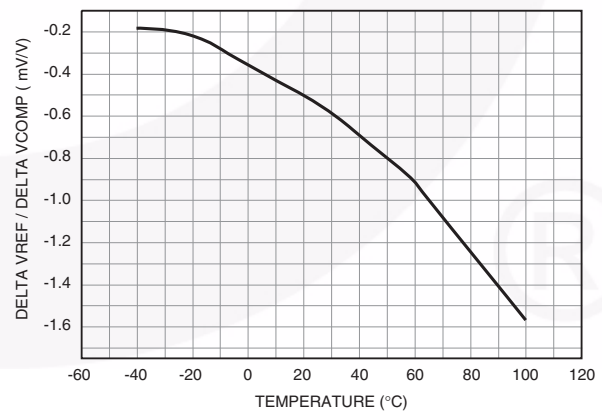
**Fig. 17 Saturation Voltage vs. Ambient Temperature**



**Fig. 18 Collector Current vs. Collector Voltage**

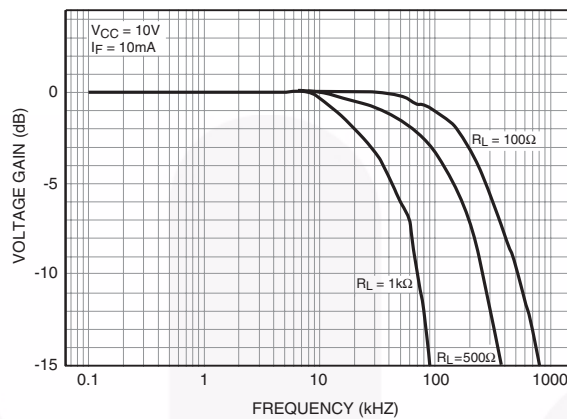


**Fig. 19 Rate of Change  $V_{REF}$  to  $V_{COMP}$  vs. Temperature**



### Typical Performance Curves (Continued)

Fig. 20 Voltage Gain vs. Frequency



## The FOD2711A

The FOD2711A is an optically isolated error amplifier. It incorporates three of the most common elements necessary to make an isolated power supply, a reference voltage, an error amplifier, and an optocoupler. It is functionally equivalent to the popular AZ431L shunt voltage regulator plus the CNY17F-3 optocoupler.

### Powering the Secondary Side

The LED pin in the FOD2711A powers the secondary side, and in particular provides the current to run the LED. The actual structure of the FOD2711A dictates the minimum voltage that can be applied to the LED pin: The error amplifier output has a minimum of the reference voltage, and the LED is in series with that. Minimum voltage applied to the LED pin is thus  $1.24V + 1.5V = 2.74V$ . This voltage can be generated either directly from the output of the converter, or else from a slaved secondary winding. The secondary winding will not affect regulation, as the input to the FB pin may still be taken from the output winding.

The LED pin needs to be fed through a current limiting resistor. The value of the resistor sets the amount of current through the LED, and thus must be carefully selected in conjunction with the selection of the primary side resistor.

### Feedback

Output voltage of a converter is determined by selecting a resistor divider from the regulated output to the FB pin. The FOD2711A attempts to regulate its FB pin to the reference voltage, 1.24V. The ratio of the two resistors should thus be:

$$\frac{R_{TOP}}{R_{BOTTOM}} = \frac{V_{OUT}}{V_{REF}} - 1$$

The absolute value of the top resistor is set by the input offset current of  $0.8\mu A$ . To achieve 1% accuracy, the resistance of  $R_{TOP}$  should be:

$$\frac{V_{OUT} - 1.24}{R_{TOP}} > 80\mu A$$

### Compensation

The compensation pin of the FOD2711A provides the opportunity for the designer to design the frequency response of the converter. A compensation network may be placed between the COMP pin and the FB pin. In typical low-bandwidth systems, a  $0.1\mu F$  capacitor may be used. For converters with more stringent requirements, a network should be designed based on measurements of the system's loop. An excellent reference for this process may be found in "Practical Design of Power Supplies" by Ron Lenk, IEEE Press, 1998.

### Secondary Ground

The GND pin should be connected to the secondary ground of the converter.

### No Connect Pins

The NC pins have no internal connection. They should not have any connection to the secondary side, as this may compromise the isolation structure.

### Photo-Transistor

The Photo-transistor is the output of the FOD2711A. In a normal configuration the collector will be attached to a pull-up resistor and the emitter grounded. There is no base connection necessary.

The value of the pull-up resistor, and the current limiting resistor feeding the LED, must be carefully selected to account for voltage range accepted by the PWM IC, and for the variation in current transfer ratio (CTR) of the opto-isolator itself.

**Example:** The voltage feeding the LED pins is +12V, the voltage feeding the collector pull-up is +10V, and the PWM IC is the Fairchild KA1H0680, which has a 5V reference. If we select a  $10K\Omega$  resistor for the LED, the maximum current the LED can see is:

$$(12V - 2.74V) / 10k\Omega = 926\mu A.$$

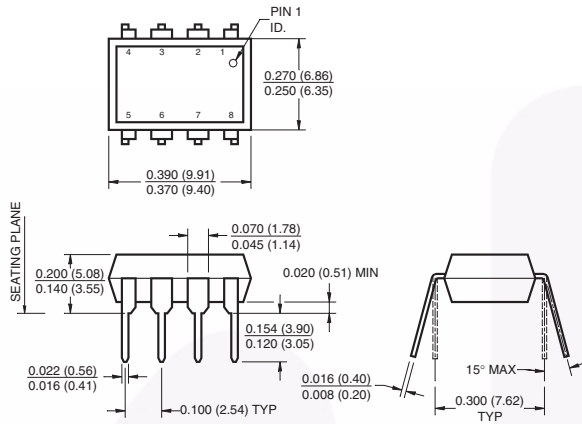
The CTR of the opto-isolator is a minimum of 100%, and so the minimum collector current of the photo-transistor when the diode is full on is also  $926\mu A$ . The collector resistor must thus be such that:

$$\frac{10V - 5V}{R_{COLLECTOR}} < 926\mu A \text{ or } R_{COLLECTOR} > 5.4K\Omega;$$

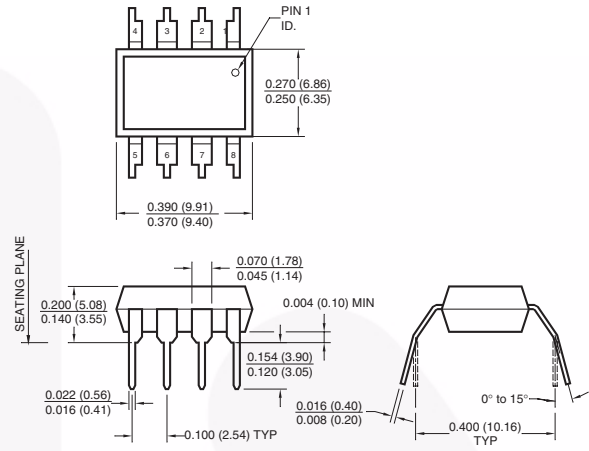
select  $10k\Omega$  to allow some margin.

## Package Dimensions

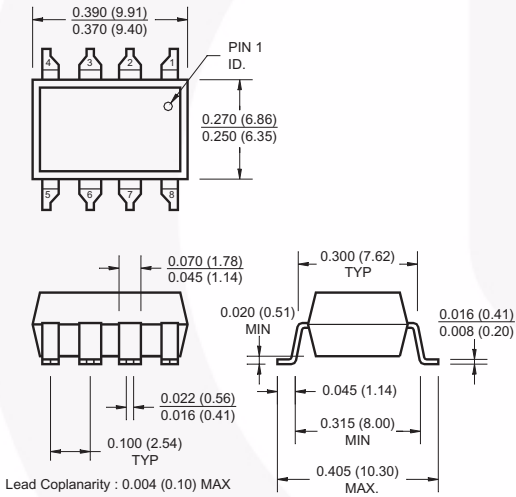
### Through Hole



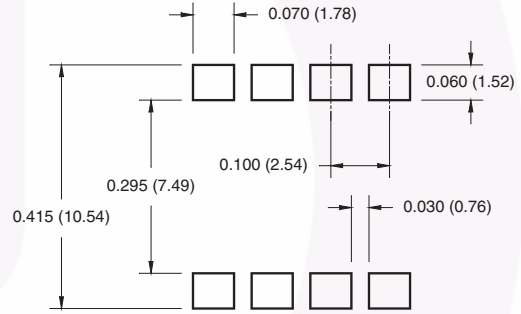
### 0.4" Lead Spacing



### Surface Mount



### 8-Pin DIP – Land Pattern



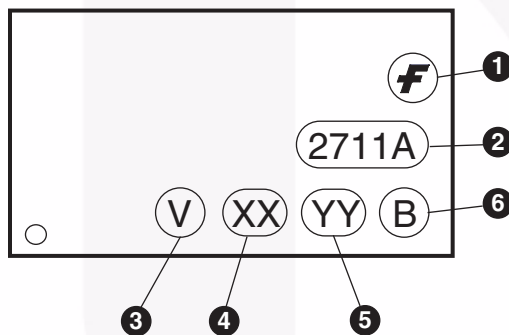
**Note:**

All dimensions are in inches (millimeters)

### Ordering Information

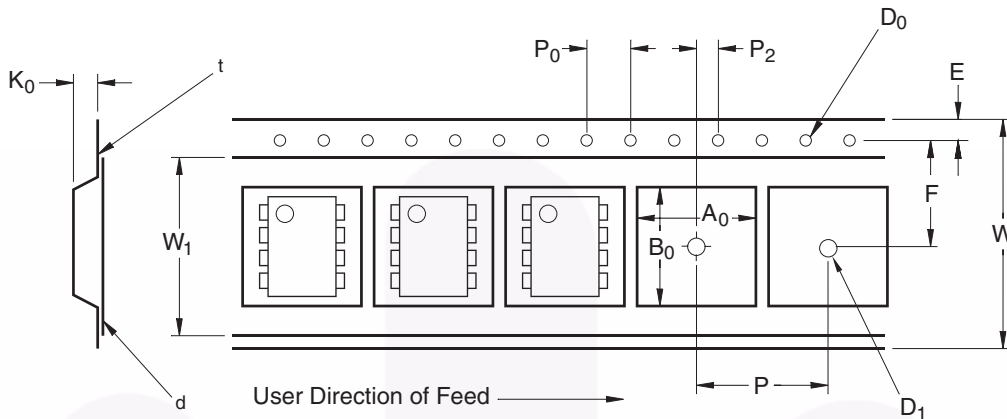
| Option    | Example Part Number | Description                           |
|-----------|---------------------|---------------------------------------|
| No Option | FOD2711A            | Standard Through Hole                 |
| S         | FOD2711AS           | Surface Mount Lead Bend               |
| SD        | FOD2711ASD          | Surface Mount; Tape and Reel          |
| T         | FOD2711AT           | 0.4" Lead Spacing                     |
| V         | FOD2711AV           | VDE0884                               |
| TV        | FOD2711ATV          | VDE0884; 0.4" Lead Spacing            |
| SV        | FOD2711ASV          | VDE0884; Surface Mount                |
| SDV       | FOD2711ASDV         | VDE0884; Surface Mount; Tape and Reel |

### Marking Information



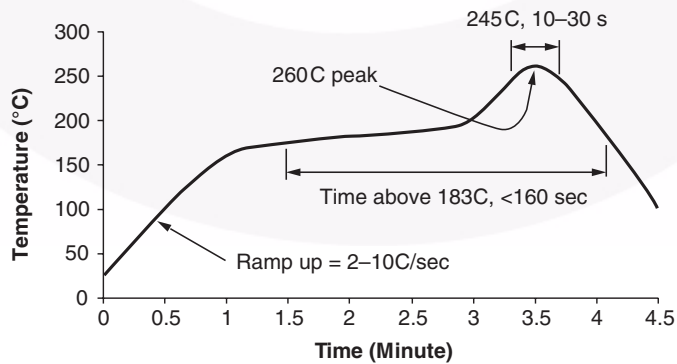
| Definitions |  |
|-------------|--|
| 1           | Fairchild logo   |
| 2           | Device number  |
| 3           | VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table) |
| 4           | Two digit year code, e.g., '03'  |
| 5           | Two digit work week ranging from '01' to '53'  |
| 6           | Assembly package code  |

## Carrier Tape Specifications



| Symbol         | Description                     | Dimension in mm |
|----------------|---------------------------------|-----------------|
| W              | Tape Width                      | 16.0 ± 0.3      |
| t              | Tape Thickness                  | 0.30 ± 0.05     |
| P <sub>0</sub> | Sprocket Hole Pitch             | 4.0 ± 0.1       |
| D <sub>0</sub> | Sprocket Hole Diameter          | 1.55 ± 0.05     |
| E              | Sprocket Hole Location          | 1.75 ± 0.10     |
| F              | Pocket Location                 | 7.5 ± 0.1       |
| P <sub>2</sub> |                                 | 4.0 ± 0.1       |
| P              | Pocket Pitch                    | 12.0 ± 0.1      |
| A <sub>0</sub> | Pocket Dimensions               | 10.30 ± 0.20    |
| B <sub>0</sub> |                                 | 10.30 ± 0.20    |
| K <sub>0</sub> |                                 | 4.90 ± 0.20     |
| W <sub>1</sub> | Cover Tape Width                | 1.6 ± 0.1       |
| d              | Cover Tape Thickness            | 0.1 max         |
|                | Max. Component Rotation or Tilt | 10°             |
| R              | Min. Bending Radius             | 30              |

## Reflow Profile



- Peak reflow temperature: 260C (package surface temperature)
- Time of temperature higher than 183C for 160 seconds or less
- One time soldering reflow is recommended



**TRADEMARKS**

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- |                          |                                     |                                       |   |
|--------------------------|-------------------------------------|---------------------------------------|---|
| AccuPower™               | F-PFS™                              | Power-SPM™                            | <p><b>SYSTEM GENERAL</b><br/>The Power Franchise®<br/>the <b>power</b> franchise<br/>TinyBoost™<br/>TinyBuck™<br/>TinyCalc™<br/>TinyLogic™<br/>TINYOPTO™<br/>TinyPower™<br/>TinyPWM™<br/>TinyWire™<br/>TriFault Detect™<br/>TRUECURRENT™<br/>" SerDes™<br/> SerDes™<br/>UHC™<br/>Ultra FRFET™<br/>UniFET™<br/>VCX™<br/>VisualMax™<br/>XS™</p> |
| Auto-SPM™                | FRFET®                              | PowerTrench®                          |   |
| Build it Now™            | Global Power Resource <sup>SM</sup> | PowerXS™                              |   |
| CorePLUS™                | Green FPS™                          | Programmable Active Droop™            |   |
| CorePOWER™               | Green FPS™ e-Series™                | QFET®                                 |   |
| CROSSVOLT™               | Gmax™                               | QS™                                   |   |
| CTL™                     | GTO™                                | Quiet Series™                         |   |
| Current Transfer Logic™  | IntelliMAX™                         | RapidConfigure™                       |   |
| DEUXPEED®                | ISOPLANAR™                          | ™                                     |   |
| Dual Cool™               | MegaBuck™                           | Saving our world, 1mW/W/kW at a time™ |   |
| EcoSPARK®                | MICROCOUPLER™                       | SignalWise™                           |   |
| EfficientMax™            | MicroFET™                           | SmartMax™                             |   |
| ESBC™                    | MicroPak™                           | SMART START™                          |   |
| Fairchild®               | MicroPak2™                          | SPM®                                  |   |
| Fairchild Semiconductor® | MillerDrive™                        | STEALTH™                              |   |
| FACT Quiet Series™       | MotionMax™                          | SuperFET™                             |   |
| FACT®                    | Motion-SPM™                         | SuperSOT™-3                           |   |
| FAST®                    | OptoHIT™                            | SuperSOT™-6                           |   |
| FastvCore™               | OPTOLOGIC®                          | SuperSOT™-8                           |   |
| FETBench™                | OPTOPLANAR®                         | SupreMOS®                             |   |
| FlashWriter®             | PDP SPM™                            | SyncFET™                              |   |
| FPS™                     |                                     | Sync-Lock™                            |   |

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**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

| Datasheet Identification | Product Status        | Definition  |
|--------------------------|-----------------------|---|
| Advance Information      | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
| Preliminary              | First Production      | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
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